

CLAIMS:

1. A method of forming a wire bond bonding a wire to a connection pad of an electronic device, comprising the steps of forming a first stitch bond on the connection pad, and forming a second stitch bond on the connection pad that is contiguous with the first stitch bond.  
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2. A method as claimed in claim 1, wherein the second stitch bond partially lies on the first stitch bond and partially lies on the connection pad.  
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3. A method as claimed in claim 1, wherein a position of the second stitch bond is offset from a position of the first stitch bond.
4. A method as claimed in claim 1, including arranging the second stitch bond such that it is oriented in a different direction relative to the orientation of the first stitch bond.  
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5. A method as claimed in claim 1, including arranging the second stitch bond such that it is oriented in a different direction relative to a length of wire connected to the wire bond.  
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6. A method as claimed in claim 1, wherein the wire is fed from a capillary, and including the step of moving the capillary in a reverse motion direction that is different to a direction that the first stitch bond is oriented after making the first stitch bond and before making the second bond.  
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7. A method as claimed in claim 6, including moving the capillary in a direction that is opposite to the reverse motion direction to a second stitch bonding position to form the second stitch bond.  
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8. A method as claimed in claim 1, including forming an additional stitch bond on the connection pad that is contiguous with the first stitch bond and/or second stitch bond.

9. A wire bond bonding a wire to a connection pad of an electronic device, comprising a first stitch bond on the connection pad and a second stitch bond on the connection pad that is contiguous with the first stitch bond.
- 5 10. A wire bond as claimed in claim 9, wherein the second stitch bond partially lies on the first stitch bond and partially lies on the connection pad.
11. A wire bond as claimed in claim 9, wherein a position of the second stitch bond is offset from a position of the first stitch bond.
- 10 12. A wire bond as claimed in claim 9, wherein the second stitch bond is oriented in a different direction relative to the orientation of the first stitch bond.
- 15 13. A wire bond as claimed in claim 9, wherein the second stitch bond is oriented in a different direction relative to a length of wire connected to the wire bond.
- 20 14. A wire bond as claimed in claim 9, including an additional stitch bond on the connection pad that is contiguous with the first stitch bond and/or second stitch bond.
15. An electronic device comprising the wire bond as claimed in claim 9.